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Electronic Patent Application Submission
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Title of Invention: BOILING TEMPERATURE DESIGN
IN PUMPED MICROCHANNEL
COOLING LOOPS
First Named Inventor: Peng Zhou
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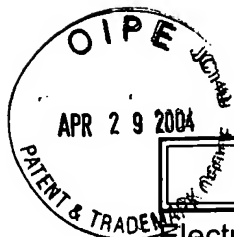
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**TRANSMITTAL**

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	BOILING TEMPERATURE DESIGN IN PUMPED MICROCHANNEL COOLING LOOPS									
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Thomas B. Haverstock Registered Number: 32571</td><td>/tbh/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney		
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Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>COOL01500B-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	COOL01500B-usidst.xml		us-ids.dtd		us-ids.xsl
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us-ids	COOL01500B-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

BOILING TEMPERATURE DESIGN IN PUMPED
MICROCHANNEL COOLING LOOPS

Application Number: 10/643638



Confirmation Number: 4432

First Named Applicant: Peng Zhou

Attorney Docket Number:

Search string: (5380956 or 5383340 or 5421943 or 5427174
or 5436793 or 5459099 or 5508234 or 5514832
or 5514906 or 5544696 or 5548605 or 5575929
or 5579828 or 5585069 or 5641400 or 5692558
or 5696405 or 5703536 or 5704416 or 5727618
or 5774779 or 5759014 or 5763951 or 5800690
or 5801442 or 5835345 or 5836750 or 5858188
or 5863708 or 5869004 or 5870823 or 5874795
or 5876655 or 5880017 or 5880524 or 5901037
or 5936192 or 5940270 or 5942093 or 5964092
or 5965001 or 5965813 or 5978220 or 5997713
or 5998240 or 6007309 or 6010316 or 6013164
or 6019882 or 6054034).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Signature

Examiner Name	Date